



## Product Change Notification - JAON-08INTZ985

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**Date:**

12 Feb 2017

**Product Category:**

Wireless Modules

**Notification subject:**

CCB 2645 Final Notice: Qualification of MMT assembly site and implement label and packing changes for RN131 products available in 44L RF Module.

**Notification text:****PCN Status:**

Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of MMT assembly site and implement label and packing changes for RN131 products available in 44L RF Module.

Change to Shield Label

Change to Tray material and Dimension

Change to BQM (Base Quantity Multiple).

Change to Packing Method

**Pre Change:**

Assembled at NGM assembly site, Top marking is sticker attached to shield, transparent shipping tray, BQM of 20, Inner/outer box dimensions 240x215x115mm/500x230x390mm, and max inner boxes per carton of 6.

**Post Change:**

Assembled at NGM or MMT assembly site, top marking is laser mark on shield, JEDEC shipping tray, BQM of 35, inner/outer box dimensions 37.1x16.2x8.8cm/39.2x34.5x19.5cm, and max inner boxes per carton of 4.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	NGM assembly site	MMT assembly site
Top Marking	Sticker Label attached to Shield	Laser Marking on Shield
Shipping Tray	Transparent Tray	JEDEC Tray
BQM (Base Quantity Multiple)	20 modules/tray	35 modules/tray
Inner Shipping Box Dimensions	240x215x115mm	37.1x16.2x8.8 cm
Outer Shipping Box Dimensions	500x230x390mm	39.2x34.5x19.5 cm
Max # of Inner Boxes/Carton	6	4

Note: Please review the attached document for pre and post details of the changes.

**Impacts to Data Sheet:**

None

**Change Impact:**



Packing and BQM (Base Quantity Multiple)

**Reason for Change:**

To improve productivity by qualifying MMT as an additional assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

August 1, 2016 (date code: 1631) – earliest customers may receive parts assembled at MMT assembly site

September 26, 2016 (date code: 1639) – earliest customers may see label and packing changes

**Time Table Summary:**

	July 2016				August 2016				September 2016				
Workweek	27	28	29	30	31	32	33	34	35	36	37	38	39
Qual Report Availability		X											
Final PCN Issue Date		X											
Estimated Implementation Date of Assembly Site					X								
Estimated Implementation Date of Label and Packing Changes													X

**Method to Identify Change:**

Traceability code, top marking, packing material

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**July 12, 2016:** Issued final notification.

**February 12, 2017:** Re-issued as final notification with an updated affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[RN131 44L RF Module - Packing Pre and Post Changes.pdf](#)

[PCN JAON-08INTZ985 Qual Report.pdf](#)

[PCN JAON-08INTZ985 Affected CPN.pdf](#)

[PCN JAON-08INTZ985 Affected CPN.xls](#)

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